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**EV GROUP WINS 3D INCITES “PROCESS OF THE YEAR” AWARD FOR NANOCLEAVE LAYER RELEASE TECHNOLOGY SET TO REVOLUTIONIZE 3D INTEGRATION**

*Prestigious industry award recognizes a technology that has made a significant contribution to the advancement of the heterogeneous integration roadmap*

**ST. FLORIAN, Austria, March 14, 2023**—EV Group (EVG), a leading supplier of wafer bonding and lithography equipment for the MEMS, nanotechnology and semiconductor markets, today announced that it has received the prestigious 2023 *3D InCites* Award in the category of “Process of the Year” in recognition of its NanoCleave™ infrared (IR) laser cleave technology. NanoCleave enables nanometer-precision layer transfer through silicon, eliminating glass substrates for advanced packaging and enabling thin-layer 3D stacking for front-end processing, including advanced logic, memory and power device formation.

Hosted by [3D InCites](#), an online community platform founded in 2009 to stir up interest in 3D integration, the *3D InCites* Awards program recognizes significant contributions to the advancement of the heterogeneous roadmap, including 3D packaging, interposer integration, advanced fan-out wafer-level packaging, MEMS and sensors, chipllets, and full system integration. This year’s awards were presented earlier today at a ceremony held during the IMAPS Device Packaging Conference in Fountain Hills, Ariz.

“It seems fitting to present EV Group with its fourth *3D InCites* Award on the 10<sup>th</sup> anniversary of the *3D InCites* Awards, as they took home their first award in the equipment category at our inaugural event in 2013,” said Françoise von Trapp, Founder, *3D InCites*. “We congratulate them on their relentless pursuit of excellence in heterogeneous integration processes and technologies.”

EVG has been providing solutions for advanced packaging and heterogeneous integration for more than 20 years, supporting revolutionary technology advances such as backside-illuminated CMOS image sensors (BSI-CIS), 3D/stacked die packaging, ultra-thin and stacked fan-out packages, and silicon photonics. The company’s industry-leading wafer-level and die-level fusion and hybrid bonding, thin-wafer handling, and lithography products are supported by EVG’s [Heterogeneous Integration Competence Center™](#), which is designed to assist customers in leveraging EVG’s process solutions and expertise to enable new and enhanced products and applications driven by advances in system integration and packaging.

NanoCleave, EVG’s latest heterogeneous integration solution, utilizes an IR laser and inorganic materials to enable laser debonding on silicon with nanometer precision. This eliminates the need for glass substrates for advanced packaging, avoiding temperature and glass carrier compatibility issues, and enables the ability to transfer ultra-thin (single micron and below) layers via carriers in front-end processing without changing the processes of record. The nanometer-precision of EVG’s new process supports advanced semiconductor device roadmaps calling for thinner device layers and packages, increased heterogeneous integration, and reduced processing costs through thin-layer transfer and the elimination of glass substrates.

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**EV GROUP RECEIVES 3D INCITES AWARD FOR PROCESS OF THE YEAR.....Page 2 of 2**

“On behalf of EV Group, I wish to extend our sincerest thanks to the panel judges and 3DInCites readers for recognizing NanoCleave™ as this year’s *3D InCites* Process of the Year,” stated Paul Lindner, executive technology director at EV Group. “Our team worked very hard to develop this revolutionary IR laser release technology, and we look forward to partnering with our customers to realize their advanced device and packaging roadmaps with the help of NanoCleave. We believe it is a true enabler for 3D and heterogeneous integration as well as material transfer in next-generation scaled transistor designs, and it is an honor to have it recognized as such by the industry.”

For more information on EVG’s NanoCleave IR laser cleave technology, please visit <https://www.evgroup.com/technologies/nanocleave/>.

**About EV Group (EVG)**

EV Group (EVG) is a leading supplier of equipment and process solutions for the manufacture of semiconductors, microelectromechanical systems (MEMS), compound semiconductors, power devices and nanotechnology devices. Key products include wafer bonding, thin-wafer processing, lithography/nanoimprint lithography (NIL) and metrology equipment, as well as photoresist coaters, cleaners and inspection systems. Founded in 1980, EV Group services and supports an elaborate network of global customers and partners all over the world. More information about EVG is available at [www.EVGroup.com](http://www.EVGroup.com).

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